

Abstract

Method, device, computer-readable storage medium and computer program element for the monitoring of a manufacturing process of a plurality of physical objects

In the case of the method, an analysis is performed by using values of at least one process parameter of the manufacturing process of the physical object and, as a result of the analysis, when they satisfy a prescribed selection criterion, physical objects are marked in such a way that the associated physical objects can be taken as a random sample for the monitoring of the manufacturing process.

List of designations

- 100 schematic block diagram of a setup of a semiconductor production installation
- 101 block of an overall manufacturing process
- 102 block of a first production area
- 103 block of a second production area
- 104 block of a third production area
- 105 block of a fourth production area
- 200 semiconductor chip production installation
- 201 multiplicity of semiconductor chip production sub-installations
- 202 path of a wafer or a lot through the semiconductor chip production installation
- 201 machine
- 301 sensor
- 302 SECS interface
- 303 PDSF file
- 304 log file
- 306 local communication network (LAN)
- 307 memory
- 308 evaluation unit
- 409 mean value of the misalignment values of a lot
- 410 variation of the distribution
- 411 wafer close to the mean value of the distribution
- 412 wafer at the maximum distance from the mean value
- 413 wafer at the border of the 1σ range of the distribution